Board Model		CPC504	CPC506	CPC508	CPC510	CPC512
Compliance with standards	**PICMG 2.0, PICMG 2.1**	v	V	V	v	
	PICMG 2.30		V	V	v	
	PICMG cPCI-S.0				v	v
Size, including mezzanines		4HP, 8HP, 12HP	4HP, 8HP, 12HP	4HP, 8HP, 12HP	4HP, 5HP*, 8HP, 12HP	4HP, 5HP*, 8HP
CPU		Intel Celeron ULV 573, 1,0 GHz Intel Core 2 Duo L7500, 1,6 GHz Intel Core 2 Duo T7500, 2,2 GHz	Intel Celeron ULV 573, 1,0 GHz, Intel Core 2 Duo L7500, 1,6 GHz Intel Core 2 Duo T7500, 2,2 GHz	Intel Atom N450, 1,66 GHz Intel Atom D510, 1,66 GHz	Intel i7-3517UE 1,7 GHz Intel i7-3555LE 2,5 GHz Intel i7-3612QE 2,1 GHz	Intel i7-3517UE 1,7 GHz Intel i7-3612LE 2,1 GHz Intel i7-3612QE 2,1 GHz
RAM		2 or 4 GB DDR II 667 SDRAM, soldered	2 or 4 GB DDR2 SDRAM 667 MHz, soldered	1 GB DDR2 SDRAM 667 MHz, soldered	4 or 8 GB DDR3L SDRAM with ECC 1600 MHz, soldered	4 or 8 GB DDR3L SDRAM with ECC 1600 MHz, soldered
Graphics Subsystem	**Type**	Integrated, 82965GME GMCH	Integrated, 82965GME GMCH	Integrated into CPU	Integrated into CPU	Integrated into CPU
	Interfaces	SVGA, 2×DVI-D	SVGA, 2×DVI-D	SVGA, LVDS (18 bit)	2xDisplay Port on the front panel 1xDisplay Port и LVDS (18/24 bit) on MIC590 mezzanine board)	2×Display Port on the front panel
	Number of independend displays	2	2	2	3	2
Communications interfaces on the front panel	**Gigabit Ethernet**	2×Gigabit Ethernet	2×Gigabit Ethernet	2×Gigabit Ethernet	2×Gigabit Ethernet	2×Gigabit Ethernet
	USB	2×USB 2.0	2×USB 2.0	2×USB 2.0	2×USB 2.0	2×USB 2.0
Storage subsystem interfaces	**On the board**	1×Secure Digital Card IDE NAND 4 GB, soldered	1×Secure Digital Card IDE NAND 4 GB, soldered	1×Compact Flash (Type 2), SATA NAND 4 GB, soldered	1×MicroSD	1×MicroSD
	On mezzanine boards and rear I/O modules	2×SATA II on MIC584	No	2×SATA II on MIC584	2×SATA II on MIC584	2×SATA III on MIC584

Board Model		CPC504	CPC506	CPC508		CPC510	CPC512
Interconnects of inter-module communication by backplane	PCI	32 bit/33 MHz	32 bit/33 MHz	32 bit/33 MHz		32-bit, 33 or 66 MHz	No
	PCI Express	No	4x channels ×1 PCI Express or one channel ×4 PCI Express	Four channels ×1 PCI Express		Two channels ×8 PCI Express (Fat Pipe) Four channels ×4 PCI Express	Two channels×8 PCI Express Gen 3.0 (Fat Pipe) Two channels ×4 PCI Express Gen 3.0 Four channels ×1 PCI Express Gen 2.0
	Gigabit Ethernet	No	2×Gigabit Ethernet software-based switching between the front panel and backplane	2×Gigabit Ethernet, software-based switching between the front panel and backplane		No	1×Gigabit Ethernet with AMT support
	SATA	No	3 × SATA II	2 × SATA I		2 × SATA III 3 × SATA II	2×SATA III 3×SATA II
	USB	No	4×USB 2.0	4×USB 2.0		8 × USB 2.0 4 × USB 3.0	10×USB 2.0 4×USB 3.0
Support of OS		FreeDOS; Windows XPe; Linux 2.6; QNX 4.25; QNX 6.5	FreeDOS; Windows XPe; Linux 2.6; QNX 4.25; QNX 6.5	FreeDOS; Windows XPe; Linux 2.6; QNX 6.5		Windows 7; Linux 2.6	Windows 7 Embedded; Linux 2.6
Energy target*		from 11,5 to 64,2 W depending on the version	from 11,5 to 64,2 W depending on the version	from 14 to 15,5 W depending on the version		From 30 to 65 W depending on the version	From 30 to 65 W depending on the version
Vibration/Single shock resistance		5g/100g	5g/100g	5g/100g		5g/100g	5g/100g
MTBF (GOST 15150-69)		More than100000 hours	More than 100000 hours	More than 140000 hours		More than 100000 hours	more than 100 000 hours
Operating temperature range**		0 ... +70 °C / -40 ... +85 °C	0 ... +70 °C / -40 ... +85 °C	-40 ... +85 °C / -50 ... +85 °C		0 ... +70 °C / -40 ... +85 °C	0…+55 °C /0…+70 °C /–40…+85°C
Mezzanine boards	Model	MIC584	MIC584	MIC584	MIC589	MIC584	MIC584
	Interfaces on the front panel	Audio IN/OUT/MIC, 2×USB 2.0, 1×RS-232, PS/2	Audio IN/OUT/MIC, 2×USB 2.0, 1×RS-232, PS/2	Audio IN/OUT/MIC, 2×USB 2.0, 1×RS-232, PS/2	2×CAN2.0 (with insulation up to 1000 V); 2×USB 2.0, 2×RS-485/422 (with insulation up to 1000 V)	Audio IN/OUT/MIC, 2×USB 2.0, 1×RS-232, PS/2	Audio IN/OUT/MIC, 2×USB 2.0, 1×RS-232, PS/2

Board Model		CPC504	CPC506	CPC508		CPC510	CPC512
	Interfaces on the board	2×SATA II, 5×RS-232/485, LPT	5×RS-232/485, LPT	2×SATA II, 5×RS-232/485, LPT	J2 connector: microphone input, line input/output; 2×CAN2.0; 2×RS-485/422; 2×RS-232; LVDS	2×SATA II, 5×RS-232/485, LPT	2×SATA II, 5×RS-232/485, LPT

***Version with conduction heat removal**

****Operating temperature range depends on the device version**

Target power consumption - is a power consumption for calculation of the system of heat-removal from the module.

Actual power consumption depends on the load and the executed application and can be less than the specified value.